



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

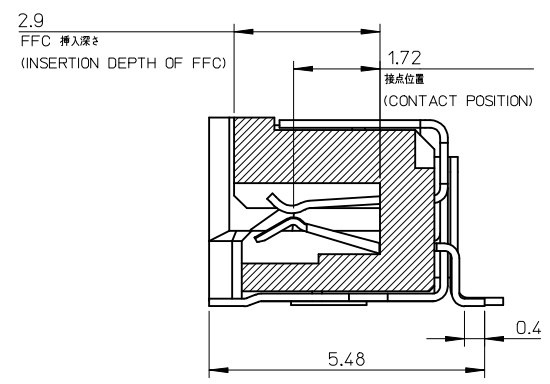
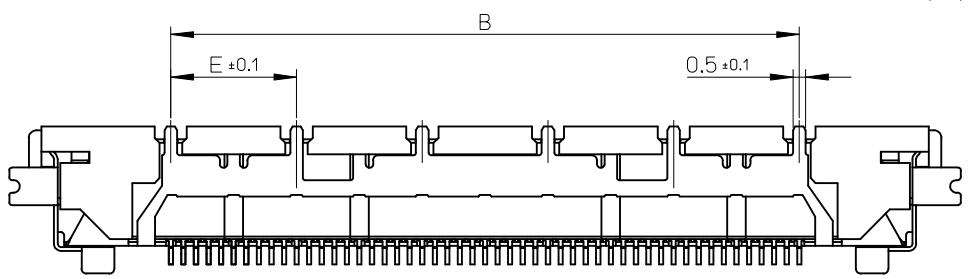
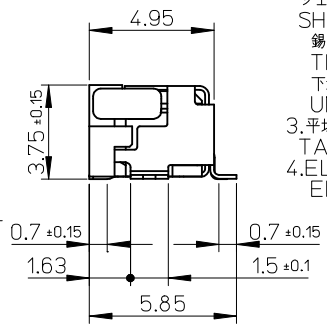
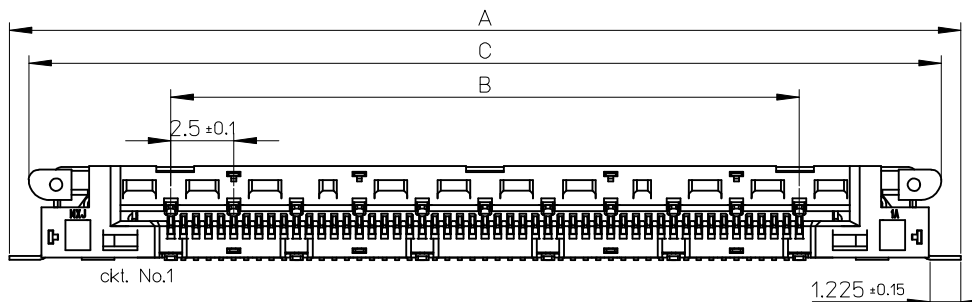
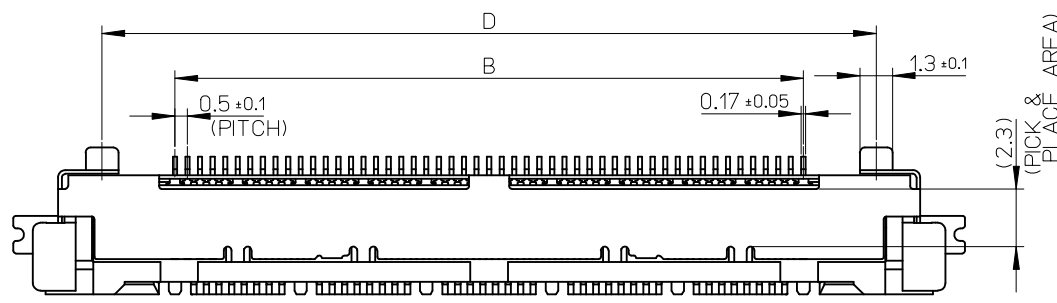
Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

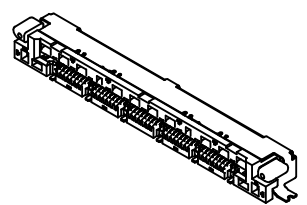
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



10 9 8 7 6 5 4 3 2 1



注記
NOTES:
1.材質
MATERIAL
ハウジング:LCP(液晶ポリマー)、黒色、ガラス充填、UL94V-0
HOUSING:LIQUID CRYSTAL POLYMER,BLACK
GLASS FILLED,UL94V-0
ターミナル:銅合金(t=0.2)
TERMINAL:COPPER ALLOY(t=0.2)
シェル:燐青銅(t=0.15)
SHELL:PHOSPHOR BRONZE(t=0.15)
2.めっき仕様
PLATING
ターミナル
TERMINAL
接点部:金めっき 0.1μm以上
CONTACT AREA: GOLD 0.1 MICROMETER MINIMUM
半田付け部:金めっき
SOLDER TAIL AREA: GOLD
下地めっき:ニッケル 1.0μm以上
UNDER PLATING:NICKEL 1.0 MICROMETER MINIMUM
シェル
SHELL
錫めっき 1.0μm以上
TIN PLATING 1.0 MICROMETER MINIMUM
下地めっき:ニッケル 1.0μm以上
UNDER PLATING:NICKEL 1.0 MICROMETER MINIMUM
3.平坦度は、0.1ミリ以下とする。
TAILS COPLANARITY TO BE 0.1 MAXIMUM.
4.ELV及びRoHS適合品
ELV AND RoHS COMPLIANT

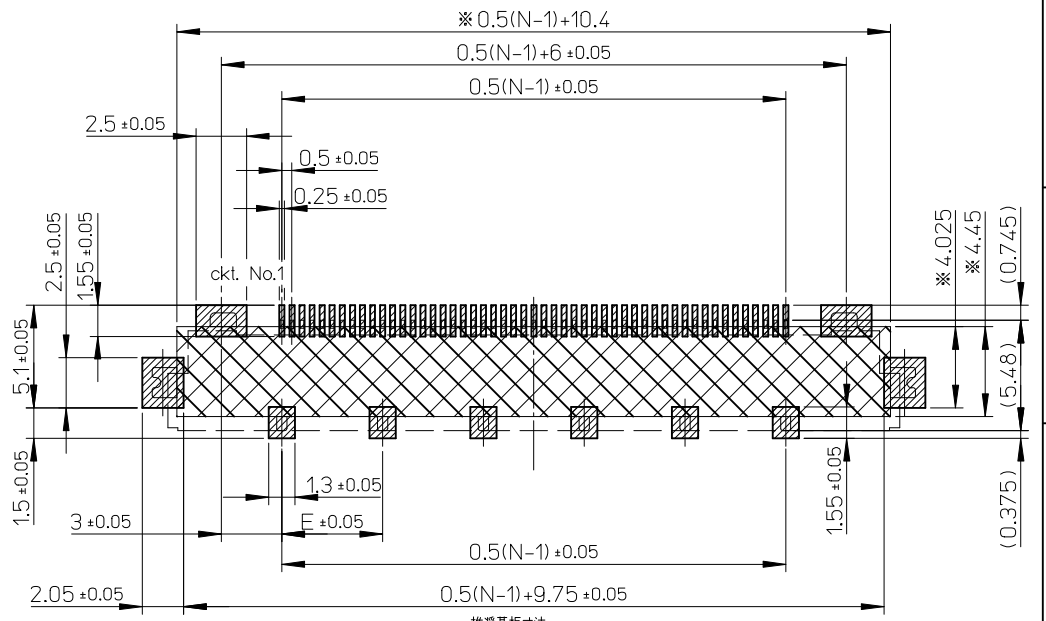
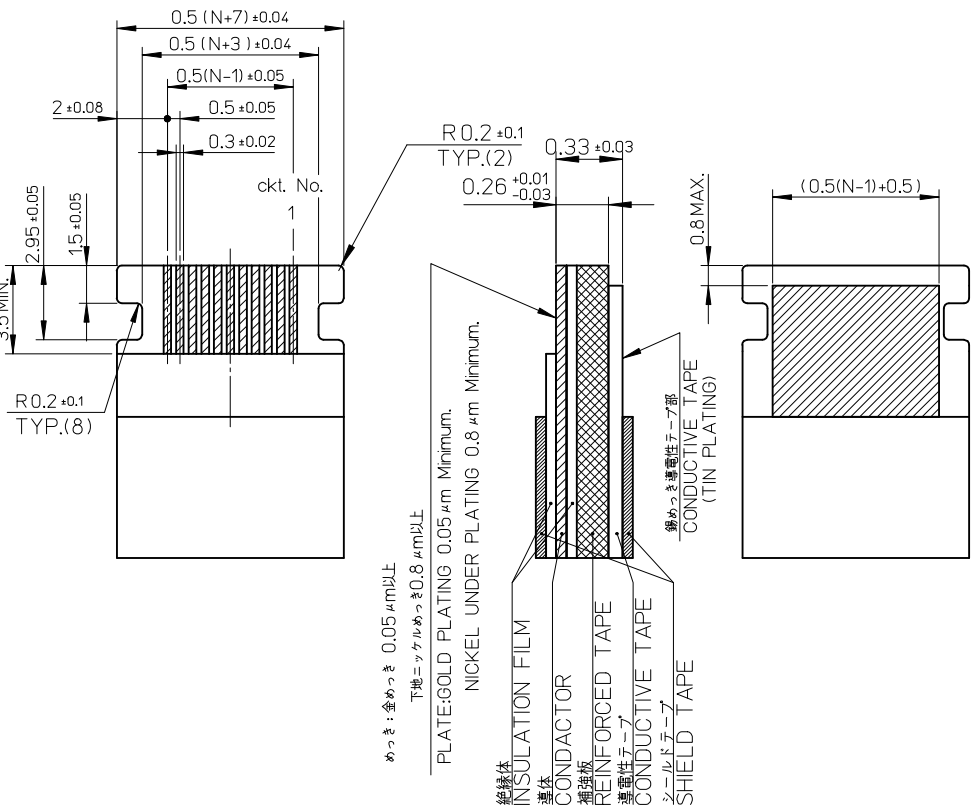


| | | | | | | |
|-----------|------|----|----|-------|-----------------------|---------|
| 5 | 30.8 | 36 | 25 | 37.85 | 503908-5100 | 51 |
| 4 | 25.8 | 31 | 20 | 32.85 | 503908-4100 | 41 |
| E | D | C | B | A | EMBOSSED TAPE PACKAGE | 極数 |
| ORDER No. | | | | | | CIRCUIT |

CONNECTOR SERIES No. 503908-**-00

| | | | | | | |
|--|---------------------------------------|--|-----------------------------|---|--|------------------------|
| REVISED EC NO.: J2015-0405 DRMKNAGUNO 2014/09/22 CHKDH I J IMA 2014/09/22 APPR: YNOGAWA 2014/09/22 | GENERAL TOLERANCES (UNLESS SPECIFIED) | | DIMENSION STYLE MM ONLY | SCALE 5:1 | DESIGN UNITS METRIC | THIRD ANGLE PROJECTION |
| | 10 UNDER | ±0.2 | DRAWN BY MOKANO | DATE 2014/07/31 | TITLE 0.5 FFC CONN. R/A NON-ZIF ASS'Y | |
| | 10 OVER 30 UNDER | ±0.25 | CHECKED BY H I I J I M A | DATE 2014/08/06 | | |
| | 30 OVER | ±0.3 | APPROVED BY YNOGAWA | DATE 2014/08/07 | | |
| REV A | ANGULAR ±1 ° | DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS | MATERIAL NO. SEE CHART | DOCUMENT NO. SD-503908-001 | SHEET NO. 1 OF 2 | |
| | | | SIZE A3 | THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION | | |

9 8 7 6 5 4 3 2



推奨基板寸法
RECOMMENDED P.W.B. PATTERN LAYOUT
※パターン禁止エリア
PATTERN PROHIBITION AREA

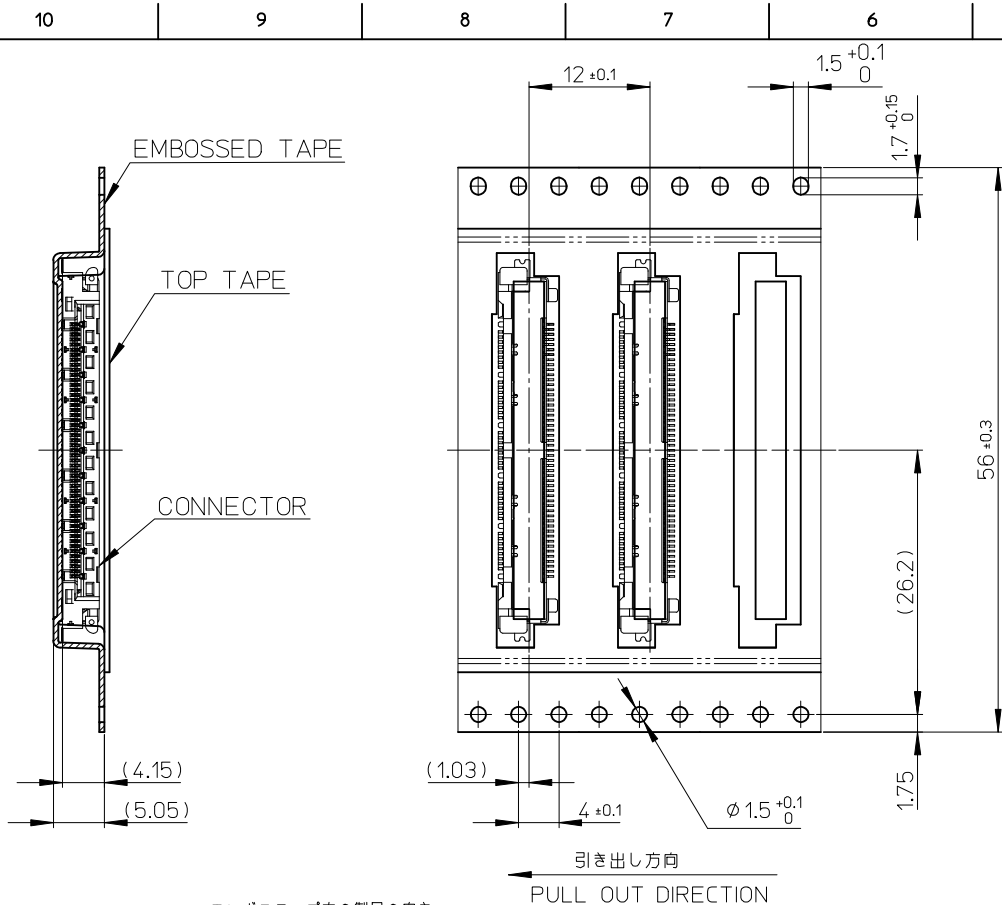
推奨メタルマスク厚: t=0.12mm
RECOMMENDED METAL MASK THICKNESS: t=0.12mm
メタルマスク開口率: 100%
APERTURE RATIO OF METAL MASK: 100%

適合する金めっきFFC推奨寸法

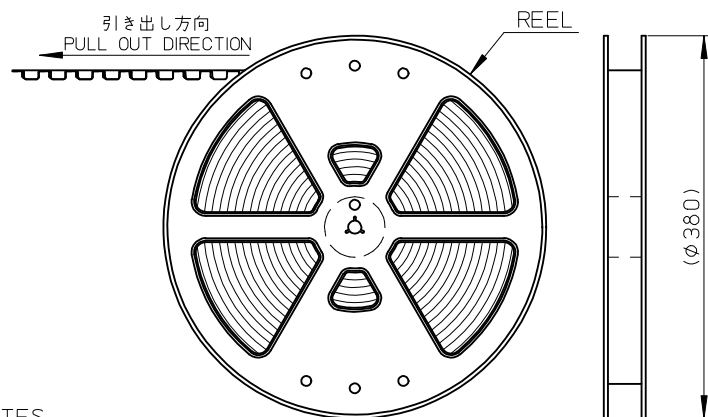
APPLICABLE FFC OF GOLD PLATING
RECOMMENDED DIMENSION

注記
NOTE
抜き方向は、導体側から補強板側を推奨致します。
RECOMMENDED PUNCHER DIRECTION:
FROM CONDUCTOR SIDE TO STIFFNER FILM SIDE.

| | | | | | | | | |
|---|--------------------|--|------------|--|--------------------|--|------------------------|--|
| SEE SHEET 1 EC NO: J2015-0405 DRWN:KNAGUMO 2014/09/22 CHKD:H IJIMA 2014/09/22 APPR:YNOGAWA 2014/09/22 | DESCRIPTION REV | GENERAL TOLERANCES (UNLESS SPECIFIED) | | DIMENSION STYLE MM ONLY | SCALE 5:1 | DESIGN UNITS METRIC | THIRD ANGLE PROJECTION | |
| | | 10 UNDER | ±0.2 | DRAWN BY MOKANO | DATE 2014/07/31 | TITLE 0.5 FFC CONN. R/A NON-ZIF ASS'Y | | |
| | | 10 OVER 30 UNDER | ±0.25 | CHECKED BY HIJIMA | DATE 2014/08/06 | molex SD-503908-001 | | |
| | | 30 OVER | ±0.3 | APPROVED BY YNOGAWA | DATE 2014/08/07 | | | |
| A | | ANGULAR ±1 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS | SIZE A3 | THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION | | | | |

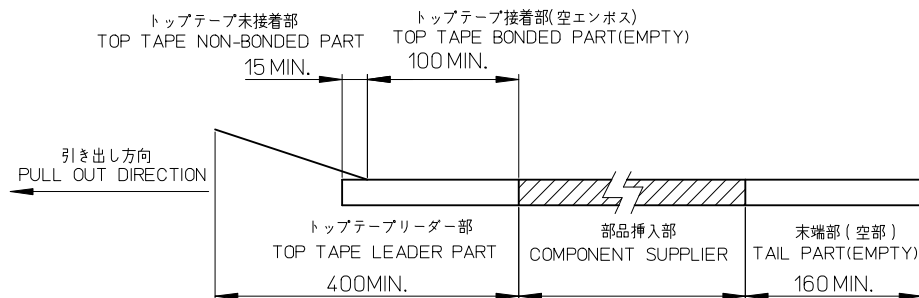


エンボステーブ内の製品の向き
DIRECTION OF CONNECTOR IN
EMBOSSSED TAPE



NOTES

- 製品の詳細については、SD-503908-001をご参照下さい。
CONNECTOR DETAILED DIMENSIONS, REFER TO SD-503908-001.
- 梱包数量：1000個/リール
NUMBER OF CONNECTORS : 1000PCS/REEL
- リードテープの長さ
LEAD TAPE LENGTH



- 材料
キャリアテープ(CARRIER TAPE) : ポリスチレン(POLYSTYRENE)
トップテープ(TOP TAPE) : PET, PE, PEF
リール(REEL) : ポリスチレン(POLYSTYRENE) <リサイクル材を含む>
<RECYCLE MATERIAL CONTAINED>
- トップテープの剥離強度については、IEC60286-3に準拠
TOP TAPE PEEL FORCE IS DEFINED BY IEC60286-3.

| | |
|---------------------|---------------|
| 503908-5100 | 51 |
| 503908-4100 | 41 |
| オーダー番号 ORDER NO. | 極数 CIRCUIT |

| | | | | | | | |
|---|---|---------------------------------------|------------|---|------------|--|---------------------------|
| PROPOSED EC NO. J2015-0196 DRWN: MOKANO CHKD: HIJIMA APPR: YNOGAWA REV 0 | DESCRIPTION 2014/08/06 2014/08/06 2014/08/07 | GENERAL TOLERANCES (UNLESS SPECIFIED) | | DIMENSION STYLE | SCALE | DESIGN UNITS | THIRD ANGLE PROJECTION |
| | | | | MM ONLY | 5:1 | METRIC | |
| | | 10 UNDER | ± 0.2 | DRAWN BY | DATE | TITLE | |
| | | 10 OVER 30 UNDER | ± 0.25 | MOKANO | 2014/07/31 | 0.5 FFC CONN. R/A NON-ZIF EMBOSSSED TAPE PACKAGE molex | |
| 30 OVER | ± 0.3 | CHECKED BY | DATE | DOCUMENT NO. | | | |
| ANGULAR ± 1 ° | | APPROVED BY | DATE | SD-503908-002 | SHEET NO. | | |
| DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS | | YNOGAWA | 2014/08/07 | SEE CHART | 1 OF 1 | | |
| | | MATERIAL NO. | | THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION | | | |
| | | SIZE | A3 | | | | |